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P-MCC8-2-3

Wire Bond Mold Package For contactless application (Memory and Controller)

Short Product Overview

May 2010

Chip Card & Security



P-MCC8-2-3 Short Product Overview		Ref.: Chip_Card_Product_Overview_11/09
Revision History: Current Version 05.10		
Previous Releases:		
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Important: Further information is confidential and on request. Please contact:

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Edition 2010
Published by Infineon Technologies AG,
Chip Card & Security
81726 Munich, Germany
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Product name	P-MCC8-2-3
Picture	
Product description	2 Antenna Contacts Wire Bond + Mold + Leadframe
Typical Applications	Payment, Access Control, e-Passport, Driver License, Transport, Government Identification, Ticketing
Pitch	9.5 mm
Dimensions	8.1 x 5.15 mm
Thickness	max. 340μm
Contact Surface	Ag
Delivery form	Tape on Reel Reel diameter 330mm
ISO - reference	ISO/IEC 7810 SO/IEC 7816-1 ISO/IEC 10373-1 / -3
Derivatives	

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